



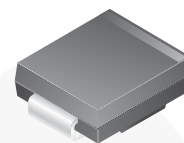
September 2014



# ES3A - ES3J Fast Rectifiers

## Features

- For Surface Mount Applications
- Glass-Passivated Junction
- Low-Profile Package
- Easy Pick and Place
- Built-in Strain Relief
- Superfast Recovery Times for High Efficiency



**SMC/DO-214AB**  
COLOR BAND DENOTES CATHODE

## Ordering Information

Part Number	Top Mark	Package	Packing Method
ES3A	ES3A	DO-214AB (SMC)	Tape and Reel
ES3B	ES3B	DO-214AB (SMC)	Tape and Reel
ES3C	ES3C	DO-214AB (SMC)	Tape and Reel
ES3D	ES3D	DO-214AB (SMC)	Tape and Reel
ES3J	ES3J	DO-214AB (SMC)	Tape and Reel

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value					Unit
		ES3A	ES3B	ES3C	ES3D	ES3J	
$V_{RRM}$	Maximum Repetitive Reverse Voltage	50	100	150	200	600	V
$I_{F(AV)}$	Average Rectified Forward Current, .375" Lead Length at $T_A = 75^\circ\text{C}$	3.0					A
$I_{FSM}$	Non-Repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine Wave	100					A
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-50 to +150					$^\circ\text{C}$

## Thermal Characteristics

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter		Value	Unit
$P_D$	Power Dissipation		1.66	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(1)</sup>	Maximum Land Pattern: 16 x 16 mm	47	$^\circ\text{C/W}$
		Minimum Land Pattern: 2.6 x 3.2 mm	125	
$R_{\theta JL}$	Thermal Resistance, Junction to Lead <sup>(1)</sup>	Maximum Land Pattern: 16 x 16 mm	12	$^\circ\text{C/W}$
		Minimum Land Pattern: 2.6 x 3.2 mm	16	

### Note:

1. Device mounted on FR-4 PCB 0.013 mm.

## Electrical Characteristics

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Value					Unit
			ES3A	ES3B	ES3C	ES3D	ES3J	
$V_F$	Maximum Forward Voltage	$I_F = 3.0\text{ A}$	0.95			1.70	V	
$t_{rr}$	Reverse Recovery Time	$I_F = 0.5\text{ A},$ $I_R = 1.0\text{ A},$ $I_{RR} = 0.25\text{ A}$	Typ.	20		35	ns	
			Max.	30		45		
$I_R$	Maximum Reverse Current at Rated $V_R$	$T_A = 25^\circ\text{C}$	10			$\mu\text{A}$		
		$T_A = 100^\circ\text{C}$	500					
$C_T$	Total Capacitance	$V_R = 4.0\text{ V}, f = 1.0\text{ MHz}$	45			pF		

## Typical Performance Characteristics

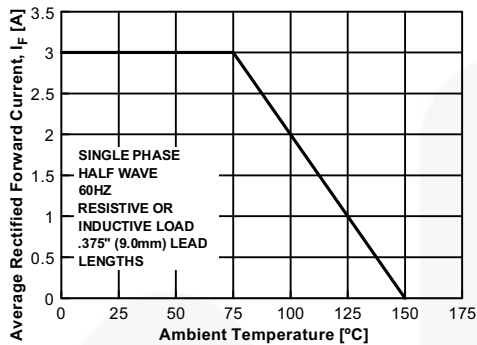


Figure 1. Forward Current Derating Curve

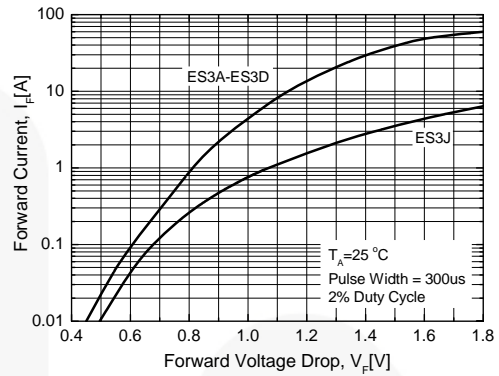


Figure 2. Forward Voltage Characteristics

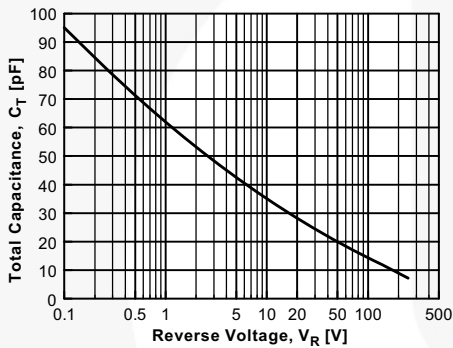


Figure 3. Total Capacitance

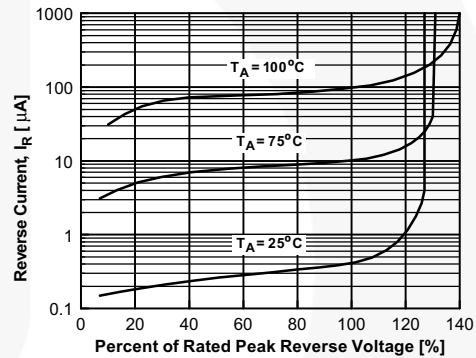
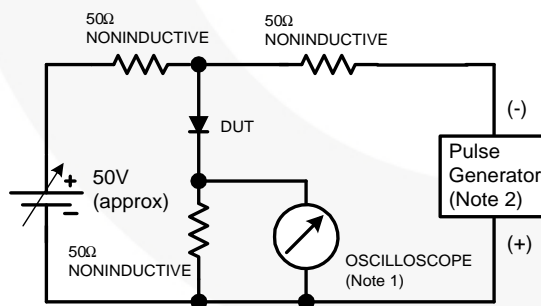


Figure 4. Reverse Current vs. Reverse Voltage



**NOTES:**

1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf.
2. Rise time = 10 ns max; Source impedance = 50 ohms.

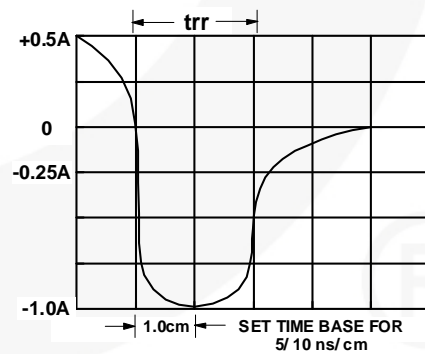


Figure 5. Reverse Recovery Time Characteristic and Test Circuit Diagram

Physical Dimension

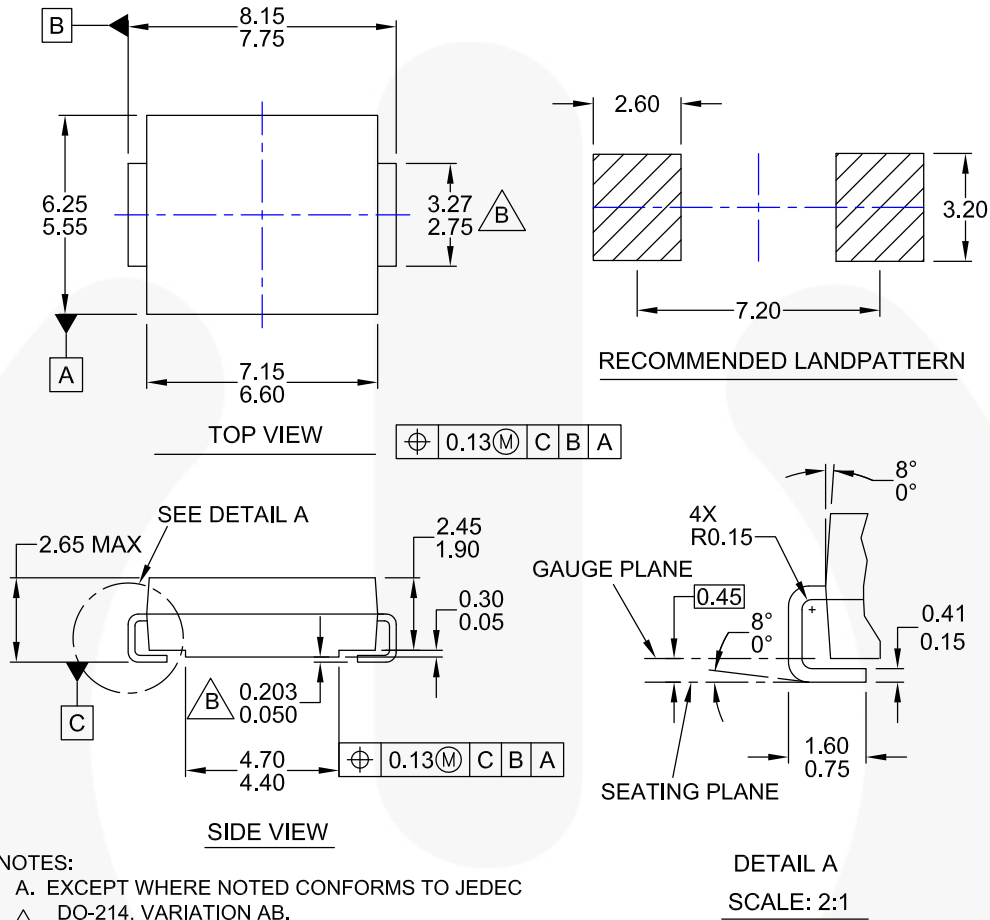


Figure 6. 2-LEAD, SMC, JEDEC DO-214, VARIATION AB (ACTIVE)



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